

Dynasolve 217



Cured Silicone Cleaning Solvent



Dynasolve 217 is a reactive formulated solvent which is used to remove cured silicones in both electronic and industrial applications.

CLEANING APPLICATIONS:

Depotting and decapsulating of electronic components
Conformal coating removal
Industrial silicone removal and cleaning

ADVANTAGES:

More efficient than acetone, MEK and other solvents
Formulated to be highly selective
Non-chlorinated
Ability to use at room temperature
High resin loading capacity allows for reuse and reduced cost of ownership

SPECIFICATIONS:

Specific gravity:	0.84
Boiling point:	>365°F (185°C)
Flash point:	201°F (94°C)

MATERIALS REMOVED:

Cured silicone

PRODUCT USAGE GUIDELINES

(SEE SDS FOR EH&S INFORMATION)

1. Ensure the part is completely free of water.
2. Immerse part in Dynasolve 217 at 150°F (65°C).
3. Once cured silicone has been removed, it is critical to rinse with alcohol prior to rinsing with water.

MATERIAL COMPATIBILITY:

Recommended materials including:

All metals
Teflon®
Polyethylene and polypropylene

Avoid materials including:

Nylon
PVC
Do not immerse in aluminum for more than 8 hours



For more information, please contact us at:

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